

FIGURE 1

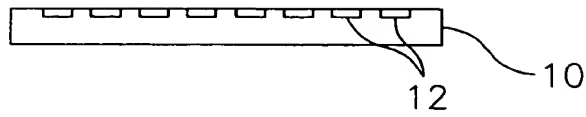


FIGURE 2A

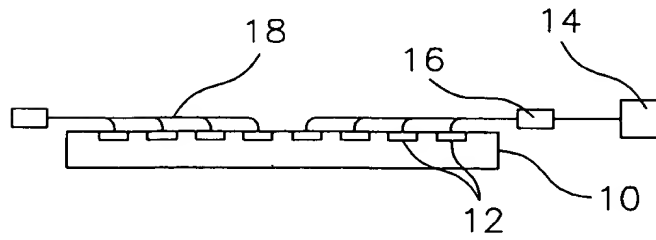


FIGURE 2B

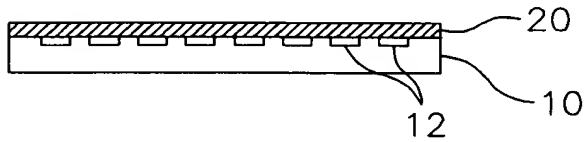


FIGURE 2C

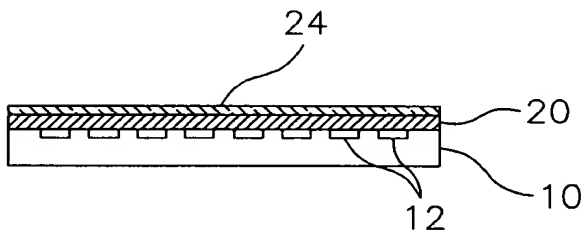


FIGURE 2D

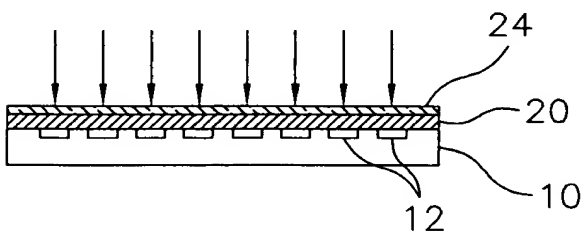


FIGURE 2E

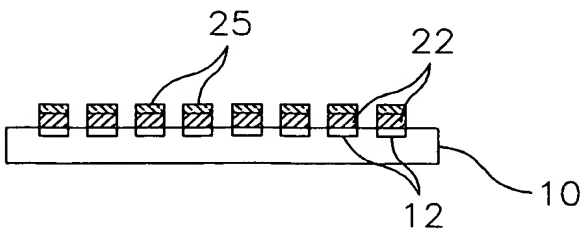


FIGURE 2F

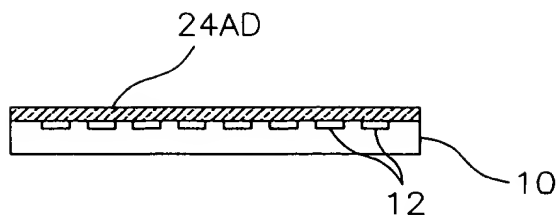


FIGURE 2G

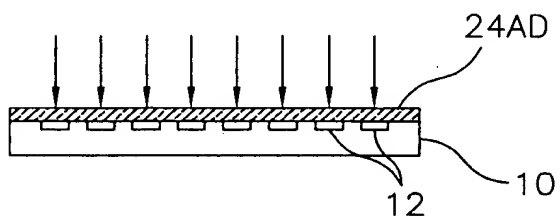


FIGURE 2H

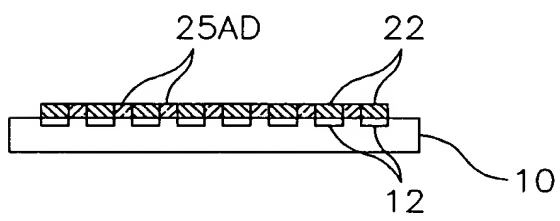


FIGURE 2I

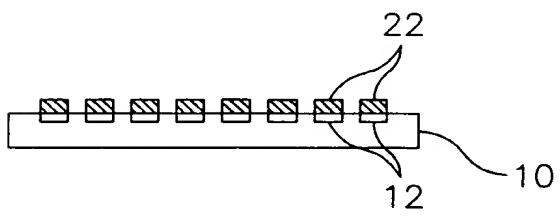


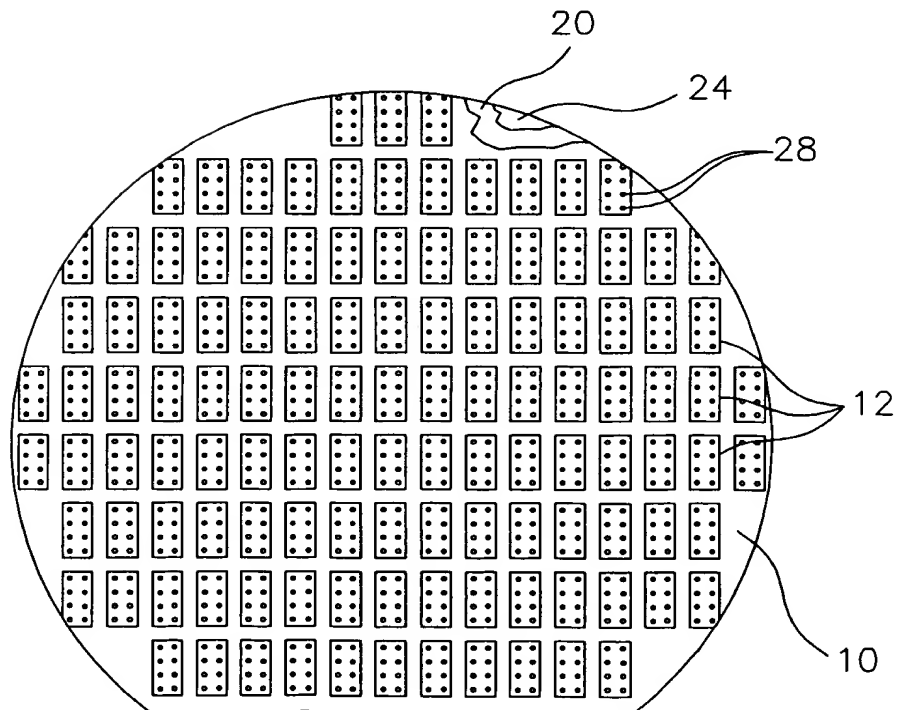
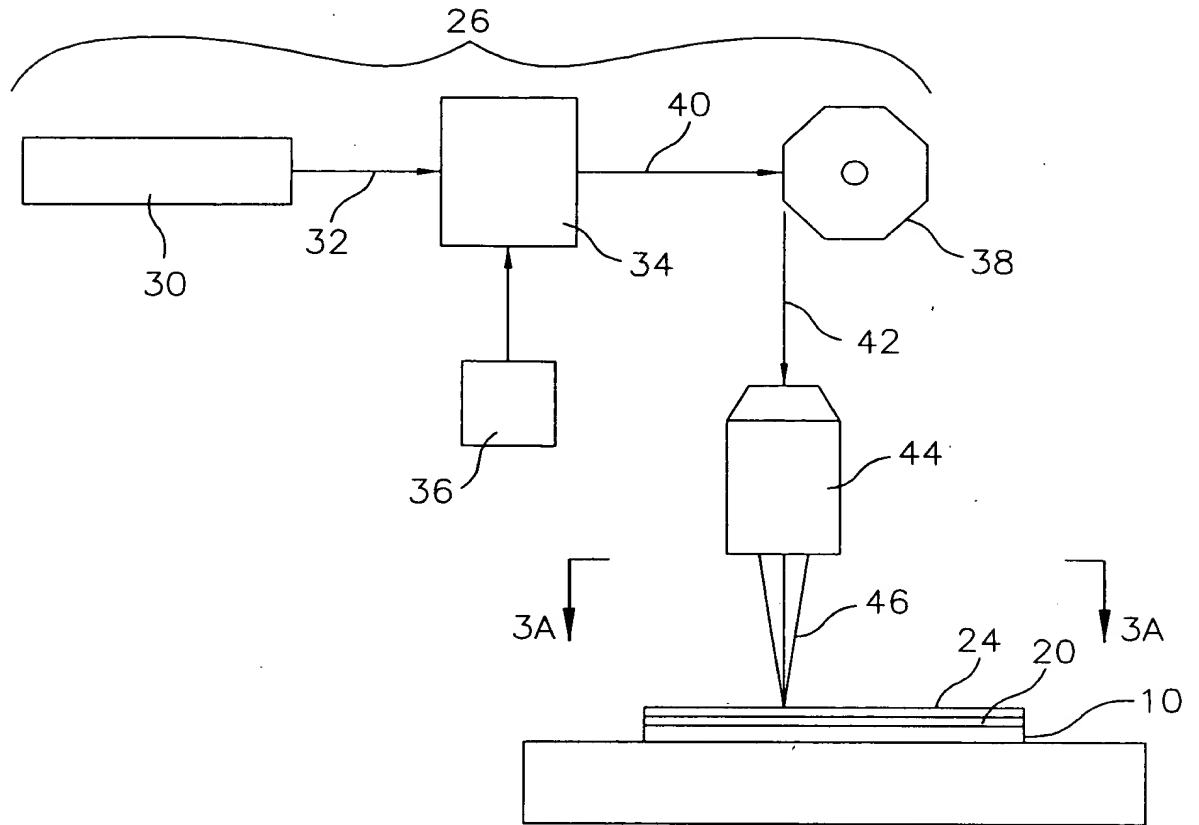
FIGURE 2J

FIG. 2G is a cross-sectional view of a device in accordance with the present invention. The device includes a substrate 10 having a series of rectangular features 12 on its top surface. A thin layer 24AD is deposited over these features.

FIG. 2H is a cross-sectional view of the device from FIG. 2G, but with vertical arrows pointing down onto the layer 24AD, indicating a process step like deposition or etching.

FIG. 2I is a cross-sectional view of the device. The features 12 are now filled with a material 25AD. A new layer 22 is formed on top of the filled features.

FIG. 2J is a cross-sectional view of the device. The features 12 are filled with material 22, and a new layer 25AD is formed on top of the entire structure.



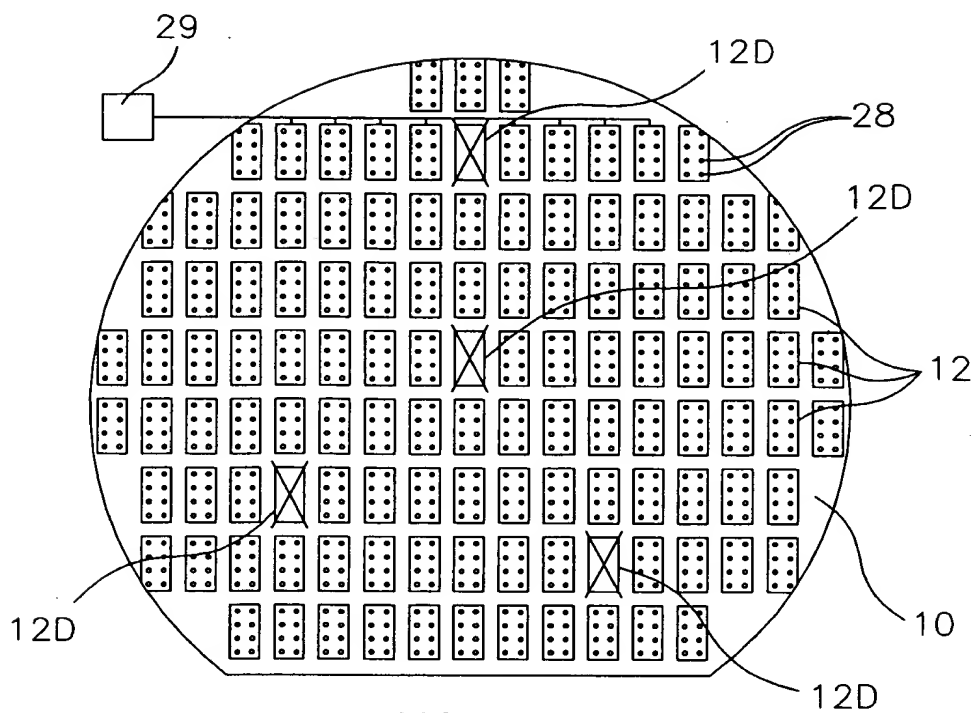


FIGURE 4

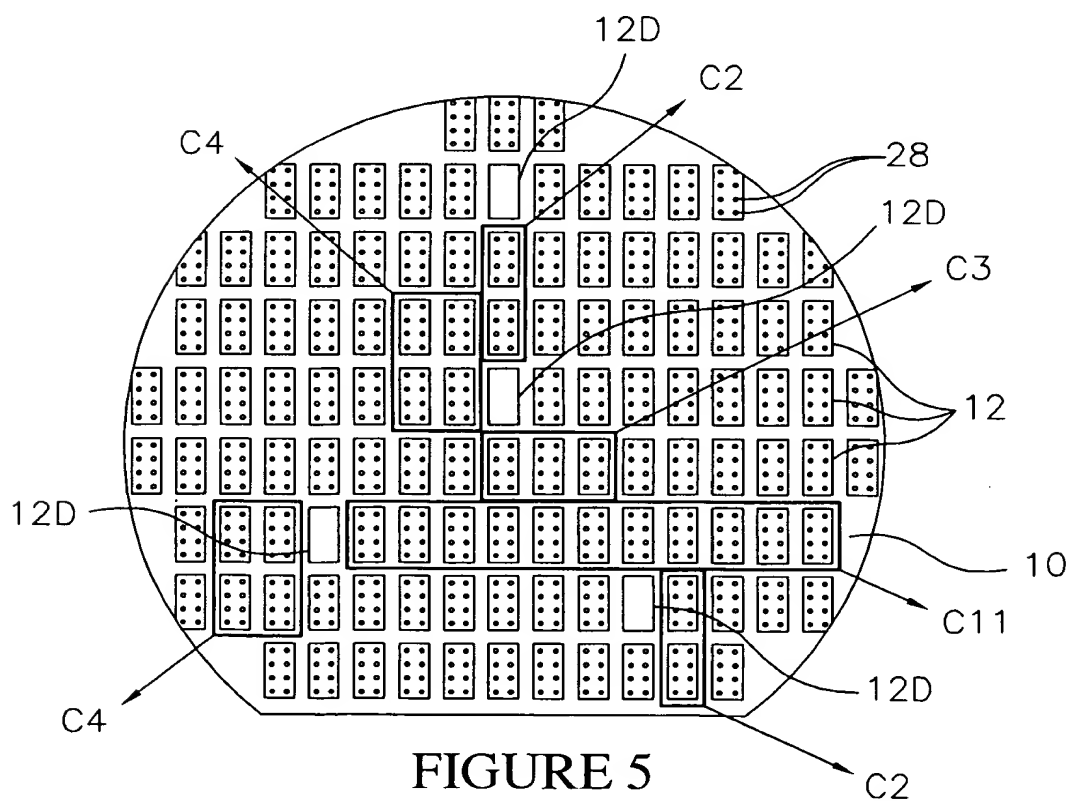


FIGURE 5

